



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|--|
| Chip Size | 0805 |
| L | 2.01mm +0.3/-0.25mm (0.079 in +0.012/-0.01 in) |
| W | 1.27mm +0.3/-0.25mm (0.05 in +0.012/-0.01 in) |
| T | 1.57mm MAX (0.062 in MAX) |
| B | 0.51mm +/-0.25mm (0.02 in +/-0.01 in) |

Packaging Specifications

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|--------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 80 |

General Information

| | |
|--------------------------|--|
| Series | SMD MIL X7R PRF32535 |
| Style | SMD Chip |
| Description | SMD, MIL-PRF-32535 |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov |
| SCIP Number | d66873f5-e54d-410c-a0cf-ebf6fcf635b5 |
| Termination | Solder Plated |
| Failure Rate | N/A |
| Qualifications | MIL-PRF-32535 M-Level |
| AEC-Q200 | No |
| Typical Component Weight | 20 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|---------------------|
| Capacitance | 0.1 uF |
| Capacitance Tolerance | 10% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 2.5% 1kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |